Korean International Semiconductor Conference & Exhibition
on Manufacturing Technology 2025
KISM 2025 BUSAN
Re:Innovation of Semiconductor Manufacturing for AI Ecosystem

[WeC1] Advanced Metrology & Inspection, Process Diagnostics & Control, and Yield Management III

Session Date	November 12 (Wed.), 2025
Session Time	09:00-10:30
Session Room	Room C (Grand Ballroom 3, 2F)
Session Chair	Dr. Hyuksang Kwon (KRISS, Korea)

[WeC1-1] [Invited] **09:00-09:30**

Next-Generation Optical Metrology for Advanced Semiconductor Packaging

Joonho You and Jaeyoung Jang (Nexensor Inc., Korea)

[WeC1-2] [Invited] **09:30-09:50**

Wafer Fracture Stress Due to Edge Cracks and Crack Inspection Method

Hyun-Jung Kim and Ju-Won Lee (Nexus1 Co., Ltd., Korea)

[WeC1-3] [Invited] **09:50-10:10**

Development of Designing Motion Profile with Advanced Jerk for Vibration Suppression and High Wafer Throughput

Heejae Byun, Kyobong Kim, Jaewon Choi, Sangoh Kim, and Janghwan Kim (SEMES, Korea)

[WeC1-4] [Invited] **10:10-10:30**

AI-Based Multi-Sensor Integrated Process Intelligence for Atomic Layer Deposition

Jihye Seo, Sung Kyu Jang (KETI, Korea), Jihun Kim, Hyoeun Kim (KETI and Sungkyunkwan Univ., Korea), Hyun-Mi Kim, Sun Gil Kim, Seul-Gi Kim (KETI, Korea), Il Hwi Lee, Nam Young Kim (SurplusGLOBAL Inc., Korea), Jong Hyun Choi, and Hyeongkeun Kim (KETI, Korea)